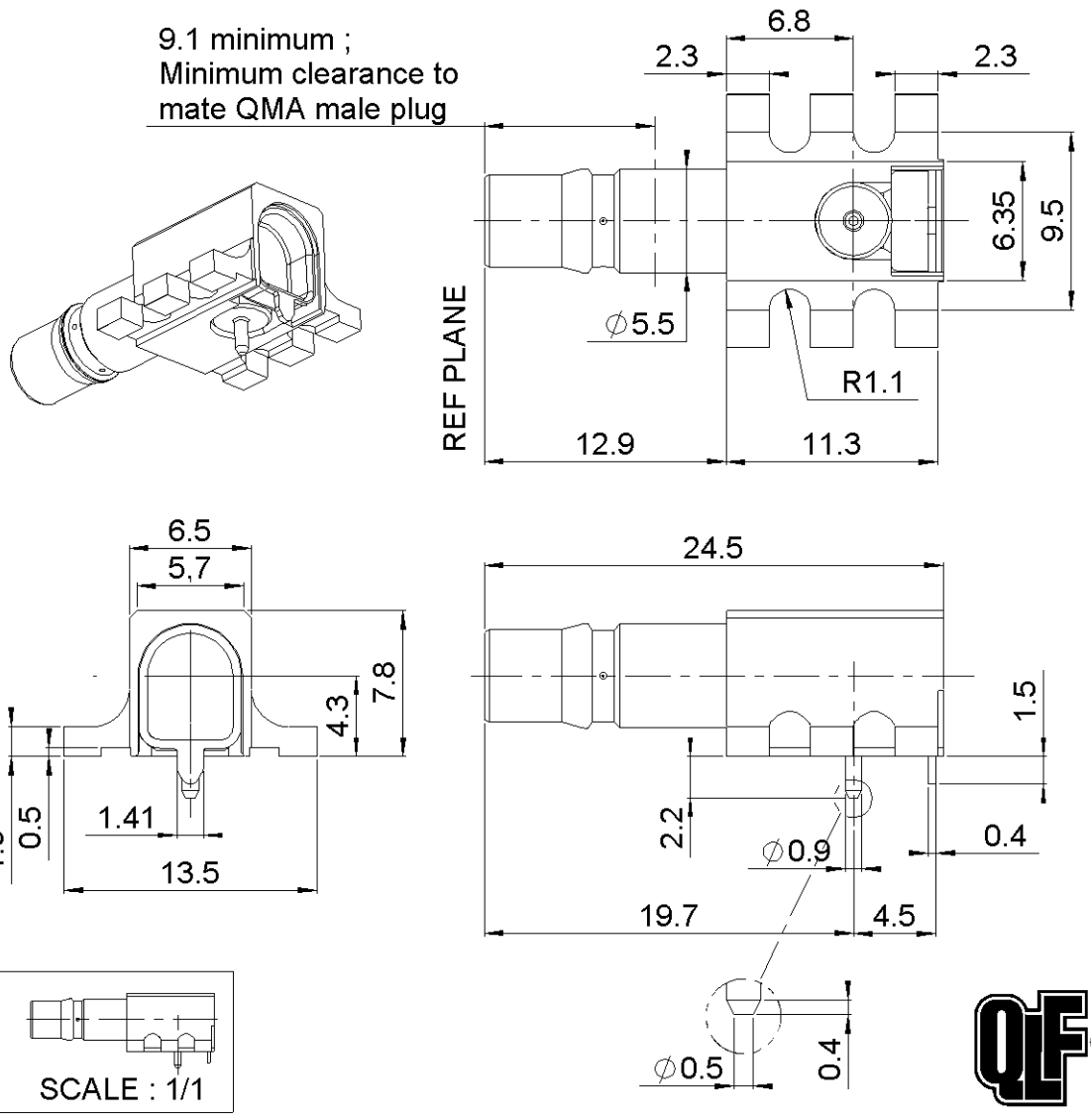
PAGE 1/5	ISSUE 02-06-16M	SERIES QMA	PART NUMBER R123682827



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
Body	**BRASS**	**NPGR**
Center contact	**BERYLLIUM COPPER**	**NPGR**
Outer contact	**-**	**-**
Insulator	**PTFE**	
Gasket	**-**	
Others parts	**BRASS**	**NPGR**
-	**-**	**-**
-	**-**	**-**

PACKAGING

Standard	Unit	Other
100	**Contact us**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance			**50**	Ω
Frequency			**0 - 6**	GHz
VSWR	**1.05***	**+**	**0.0000**	x F(GHz) Maxi
Insertion loss			**0.05**	√F(GHz) dB Maxi
RF leakage		- (	**80****	- F(GHz)) dB Maxi
Voltage rating			**350**	Veff Maxi
Dielectric withstanding voltage			**1000**	Veff mini
Insulation resistance			**5000**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	**27**	N mini
Axial force – Opposite end	**27**	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm
Mating life	**100**	Cycles mini
Weight	**5.9500**	g

ENVIRONMENTAL

Operating temperature	**-40/+105**	°C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

SPECIFICATION

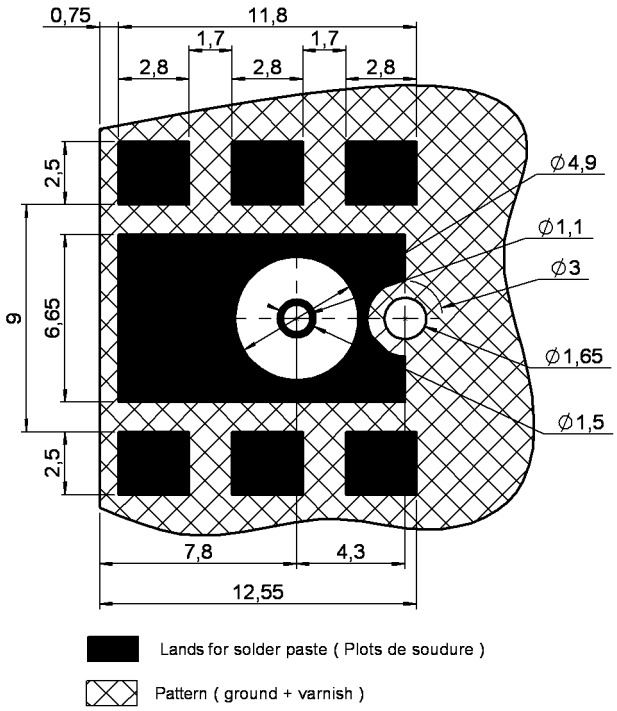
OTHER CHARACTERISTICS

Assembly instruction:

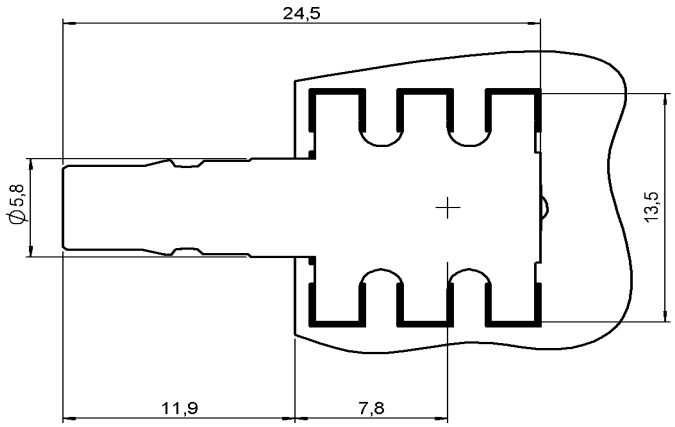
Others:
***VSWR: up to 3GHz; 3-6GHz, 1.1 Max**
****RF leakage:Interf. only:3<F<6GHz:>70dB**

QMA SERIE - INFORMATIONS

Thickness of PCB = 0.063 (1.6mm).
The material of PCB is the epoxy resin of glass fabrics bacs (Er = 4.8). The solder resist should be printed except for the land pattern on the PCB.



SHADOW OF QUICLOCK RECEPTACLE FOR VIDEO CAMERA



SOLDER PROCEDURE

1. Deposit solder paste 'Sn95 Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.

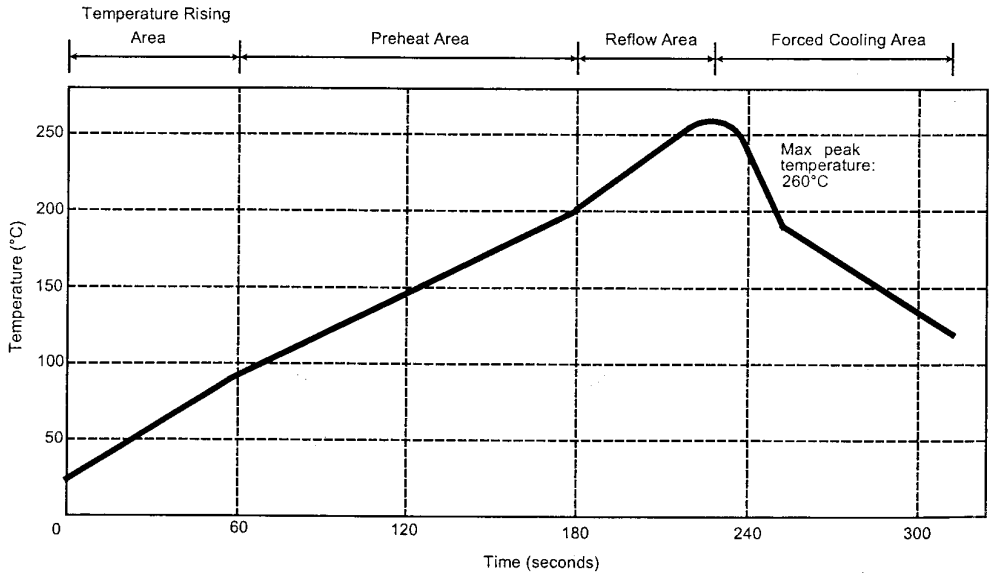
2. Placement of the receptacle on the mounting zone with an automatic 'pick and place' machine. Video camera is preferred to check the positioning of the component (See page 3). Adhesive agents are forbidden on the receptacle.

3. Soldering by infra-red reflow. We give under, the typical profile to use.

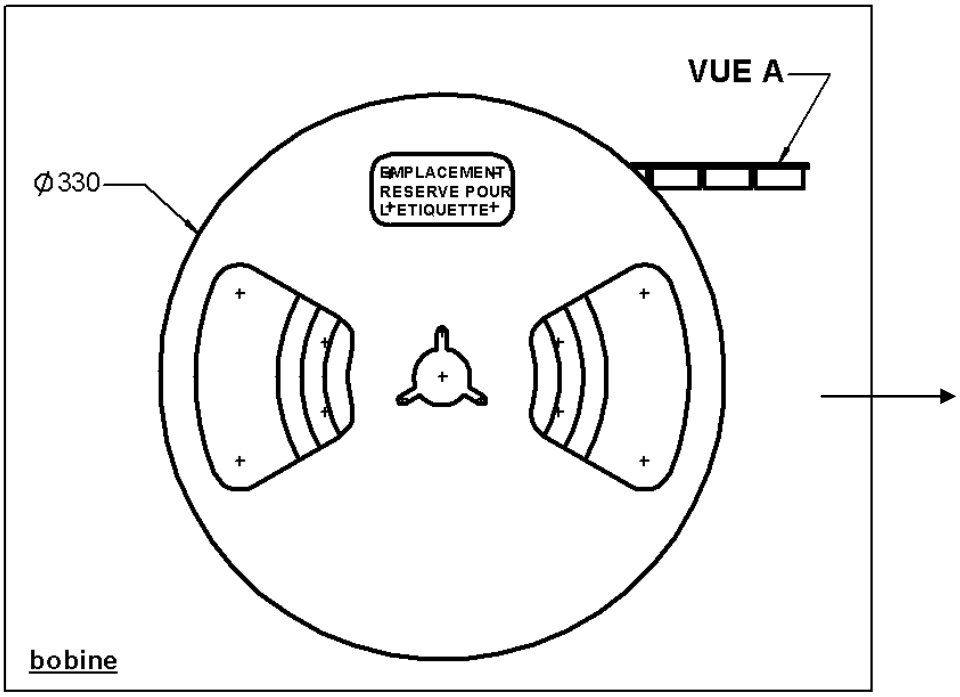
4. Cleaning of the printed circuits board.

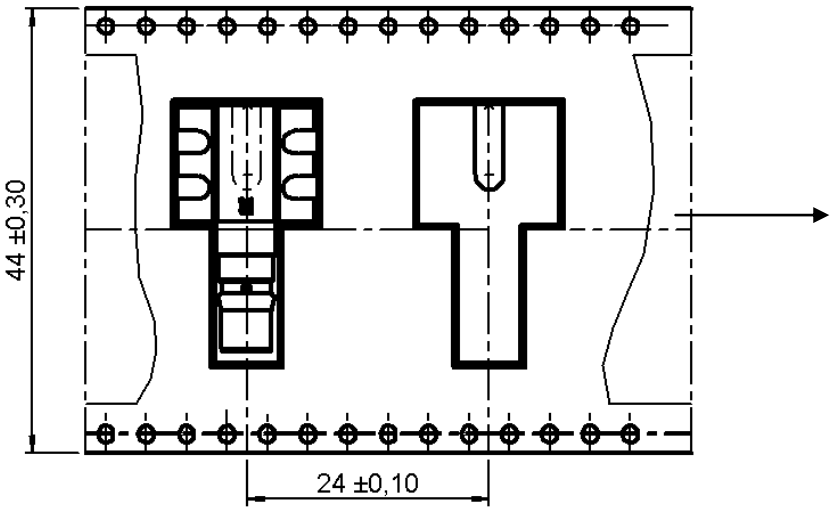
5. Checking of solder joints and position of the components by visual inspection.

TEMPERATURE PROFIL



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec





Vue A (ech : 1.5)

Direction of the tape